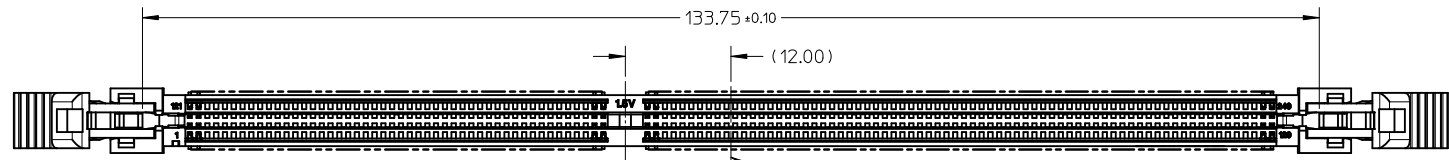


NOTES:

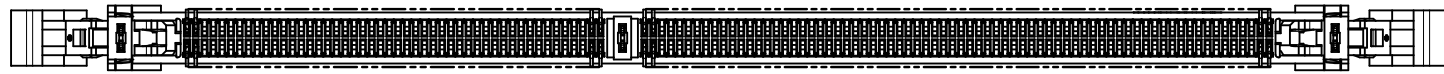
- MATERIAL : HOUSING - LCP, GLASS FILLED, UL 94V-0
COLOUR : BLACK.
LATCH - NYLON, GLASS FILLED, UL 94V-0
COLOUR : SEE TABLE ON SHEET 6.
TERMINAL : COPPER ALLOY.
- FINISHES - SEE TABLE ON SHEET 6.
- PRODUCT SPECIFICATION : SEE TABLE ON SHEET 6.
- PACKAGING SPECIFICATION: PRODUCT SHALL BE PACKED IN TRAY,
SEE SHEET 6.
- CARD SLOT ACCEPTS 1.27±0.10MM MODULE THICKNESS
(MEASURED FROM P.C. PADS).
- MOLEX LOGO, DATE & PART NO. INDICATED ON HOUSING.
- MODULE SEATING PLANE FROM TOP OF PCB.
- KEEP OUT ZONE RESERVED FOR LATCH.
- KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR
(INCLUDED LATCHES IN OPENING POSITION) IS MOUNTED ON THE PCB.
- KEEP OUT ZONE AS PER JEDEC SO-007.

P&P CAP UPDATED EC NO: S2011-0823 DRWN: JAKEEWEW 2011/03/17 CHKD: CCTEH 2011/04/07 APPR: SILENI 2011/04/07	QUALITY SYMBOLS F _A =0 F _B =0 F _C =0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY CGTAN	DATE 2008/02/11	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL SMT LOW-LLCR, STD HEIGHT			
		4 PLACES	± ---	± ---	CHECKED BY YTYANG01	DATE 2008/05/23	MOLEX INCORPORATED			
		3 PLACES	± ---	± ---	APPROVED BY SHLENI	DATE 2008/05/23	DOCUMENT NO. SD-78378-001		SHEET NO. 1 OF 6	
			2 PLACES	± 0.20	± ---	SEE TABLE				
			1 PLACE	± ---	± ---	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
			ANGULAR ± 1 °							
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							

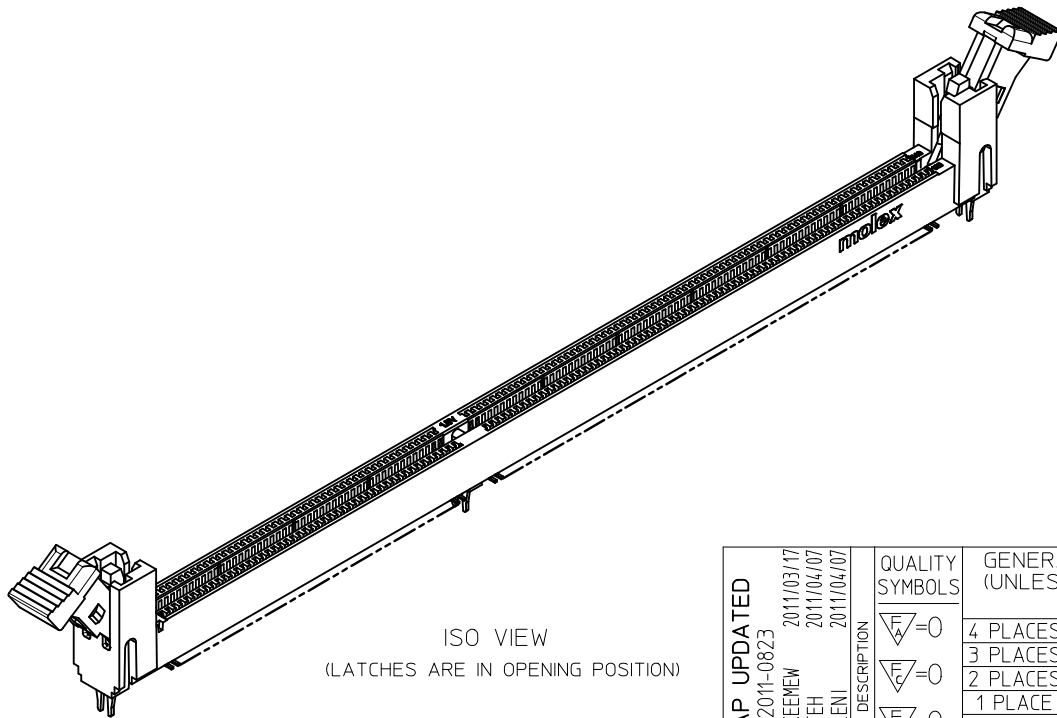
10 9 8 7 6 5 4 3 2 1



TOP VIEW
(LATCHES ARE IN OPENING POSITION)
CENTER LINE OF 128.60 MIN FEATURE



BOTTOM VIEW
(LATCHES ARE IN OPENING POSITION)

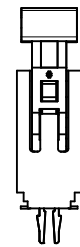
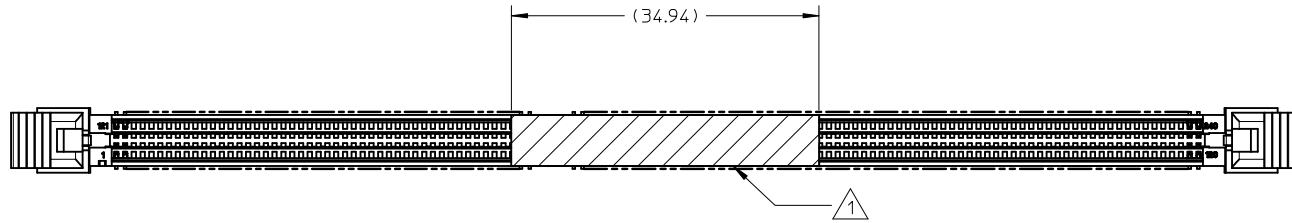


ISO VIEW
(LATCHES ARE IN OPENING POSITION)

P&P CAP UPDATED EC NO: S2011-0823 DRWN: JAKEEVEW 2011/03/17 CHKD: CCTEH 2011/04/07 APPR: SHLENI 2011/04/07	DESCRIPTION F _A =0 F _C =0 F _P =0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
				DRAWN BY CGTAN	DATE 2008/02/11	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL SMT LOW-LLCR, STD HEIGHT			
				4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± ---	CHECKED BY YTYANG01	DATE 2008/05/23	MOLEX INCORPORATED		
				ANGULAR ± 1 °	APPROVED BY SHLENI	DATE 2008/05/23	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-78378-001	SHEET NO. 2 OF 6
B3	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

9 8 7 6 5 4 3 2 1

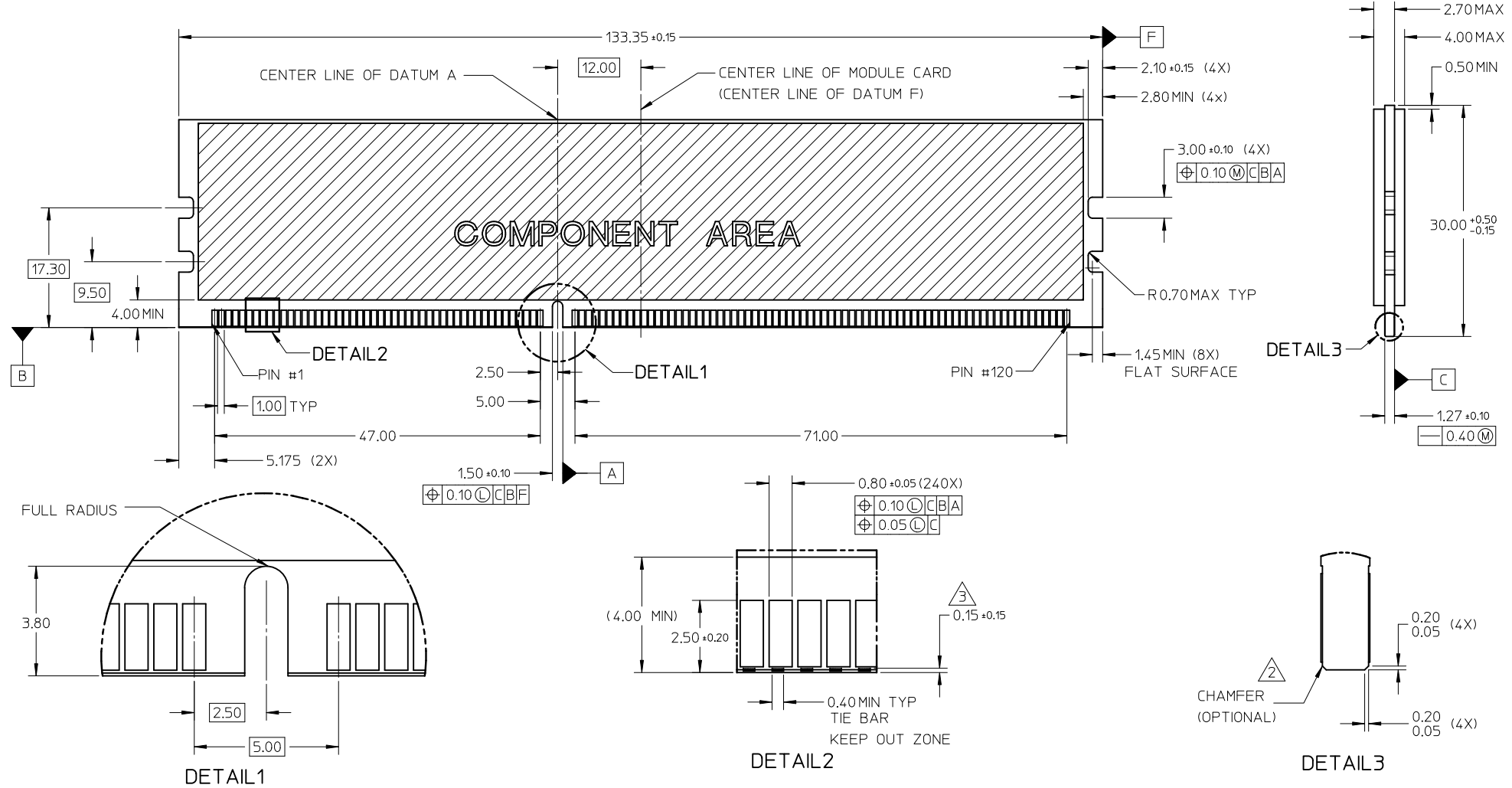
VIEWS WITH PICK & PLACE CAP



1. AREA FOR PICK AND PLACE

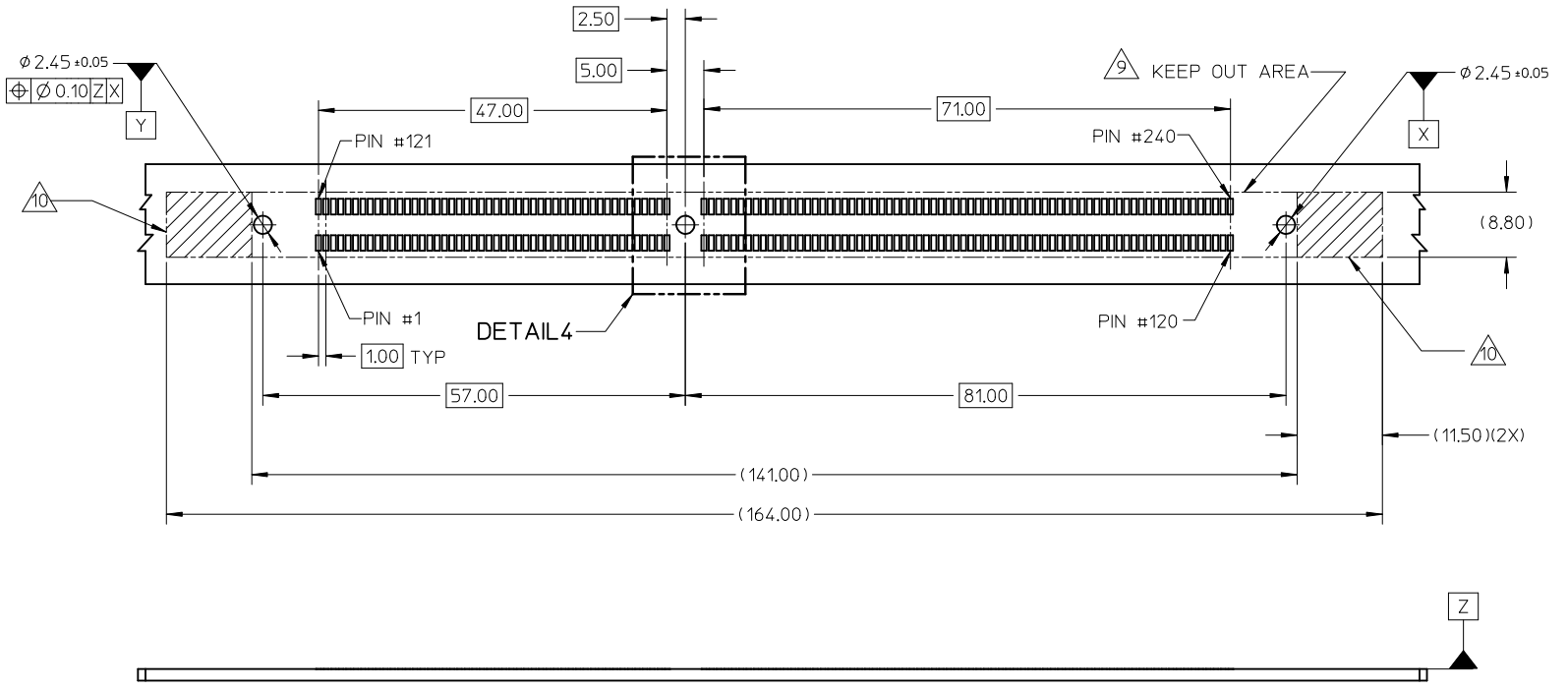
P&P CAP UPDATED EC NO: S2011-0823 DRWN: JAKEEM 2011/03/17 CHKD: CCTH 2011/04/07 APPR: SHLENI 2011/04/07	QUALITY SYMBOLS $\nabla_F = 0$ $\nabla_E = 0$ $\nabla_A = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
				MM ONLY	NTS	METRIC		
				DRAWN BY	DATE	TITLE		
				CHECKED BY	DATE	DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL SMT LOW-LLCR, STD HEIGHT		
B3	DESCRIPTION REV	4 PLACES	± ---	± ---	CGTAN	2008/02/11	MOLEX INCORPORATED DOCUMENT NO. SD-78378-001 SHEET NO. 3 OF 6	
		3 PLACES	± ---	± ---	YTYANG01	2008/05/23		
		2 PLACES	± 0.20	± ---	SHLENI	2008/05/23		
		1 PLACE	± ---	± ---	APPROVED BY DATE MATERIAL NO. DATE			
		ANGULAR ± 1 °		SEE TABLE				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

MODULE CARD
 DDR3 DUAL IN-LINE MEMORY MODULE FAMILY 1.00MM CONTACT CENTERS
 (JEDEC MO-269, ISSUE B, APRIL/06)

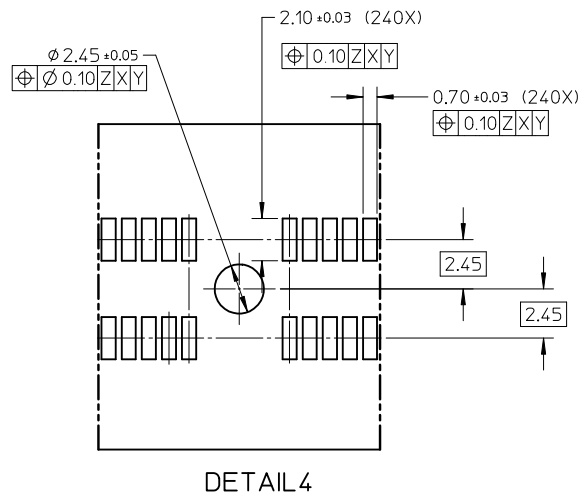


NOTES:
 1. RECOMMENDED PLATING FOR CONTACT PADS:
 PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN OVER 2.00 MICROMETERS NICKEL.
 ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING OVER 2.00 MICROMETERS NICKEL MUST USE AN ELECTRONIC CONTACT GRADE CORROSIVE BARRIER LUBRICANT.
 2. CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS.
 3. LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS.

P&P CAP UPDATED EC NO: S2011-0823 DRWN: JAKEEWEW 2011/03/17 CHKD: CCTEH 2011/04/07 APPR: SHLENI 2011/04/07	QUALITY SYMBOLS $F_A=0$ $F_G=0$ $F_B=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± ---	mm INCH	DRAWN BY CGTAN	DATE 2008/02/11	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL SMT LOW-LLCR, STD HEIGHT			
		3 PLACES ± --- ± ---	± 0.20 ± ---	CHECKED BY YTYANG01	DATE 2008/05/23	MOLEX INCORPORATED			
		2 PLACES ± --- ± ---	± --- ± ---	APPROVED BY SHLENI	DATE 2008/05/23	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-78378-001	SHEET NO. 4 OF 6	
1 PLACE ± --- ± ---	± --- ± ---	ANGULAR ± 1°		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					
B3	REV	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



RECOMMENDED PCB THICKNESS 1.57MM ~ 3.18MM
 RECOMMENDED STENCIL THICKNESS = 150 MICROMETERS



P&P CAP UPDATED EC NO: S2011-0823 DRWN: JAKEENW 2011/03/17 CHKD: CCTEH 2011/04/07 APPR: SHLENI 2011/04/07	QUALITY SYMBOLS $F_A=0$ $F_C=0$ $F_B=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
			mm	INCH	DRAWN BY CGTAN	DATE 2008/02/11	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL SMT LOW-LLCR, STD HEIGHT		
		4 PLACES	± ---	± ---	CHECKED BY YTYANG01	DATE 2008/05/23	MOLEX INCORPORATED DOCUMENT NO. SD-78378-001 SHEET NO. 5 OF 6		
		3 PLACES	± ---	± ---	APPROVED BY SHLENI	DATE 2008/05/23			
2 PLACES	± 0.20	± ---	ANGULAR ± 1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				
1 PLACE	± ---	± ---	SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

PART NO.	VOLTAGE KEY POS.	PLATING OPTION	PICK & PLACE CAP	LATCH COLOR	PACKAGING SPECIFICATION	PRODUCT SPECIFICATION
78378-0001	CENTER (1.5V)	0.76µM (30µNCH) MIN. GOLD ON CONTACT. 2.54µM (100µNCH) MIN. PURE TIN ON SOLDERTAIL. 1.27µM (50µNCH) MIN. NICKEL UNDERPLATE.	NO	BLACK	PK-78378-002	PS-78378-001
78378-0002				PK-78378-001		
78378-0003				NATURAL (OFF-WHITE)	PK-78378-002	
78378-0004				PK-78378-001		
78378-0051			YES	BLACK	PK-78378-002	
78378-0052				PK-78378-001		
78378-0053				NATURAL (OFF-WHITE)	PK-78378-002	
78378-0054				PK-78378-001		
78378-0201		0.38µM (15µNCH) MIN. GOLD ON CONTACT. 2.54µM (100µNCH) MIN. PURE TIN ON SOLDERTAIL. 1.27µM (50µNCH) MIN. NICKEL UNDERPLATE.	NO	BLACK	PK-78378-002	PS-78378-002
78378-0202				PK-78378-001		
78378-0203				NATURAL (OFF-WHITE)	PK-78378-002	
78378-0204				PK-78378-001		
78378-0251			YES	BLACK	PK-78378-002	
78378-0252				PK-78378-001		
78378-0253	NATURAL (OFF-WHITE)			PK-78378-002		
78378-0254	PK-78378-001					

P&P CAP UPDATED EC NO: S2011-0823 DRWN: JAKEEW 2011/03/17 CHKD: CCTEH 2011/04/07 APPR: SHLENI 2011/04/07	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		$\nabla = 0$ $\nabla = 0$ $\nabla = 0$	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1°	DRAWN BY DATE CGTAN 2008/02/11 CHECKED BY DATE YTYANG01 2008/05/23 APPROVED BY DATE SHLENI 2008/05/23	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL SMT LOW-LLCR, STD HEIGHT		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE TABLE	MOLEX INCORPORATED DOCUMENT NO. SD-78378-001	SHEET NO. 6 OF 6		
		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				